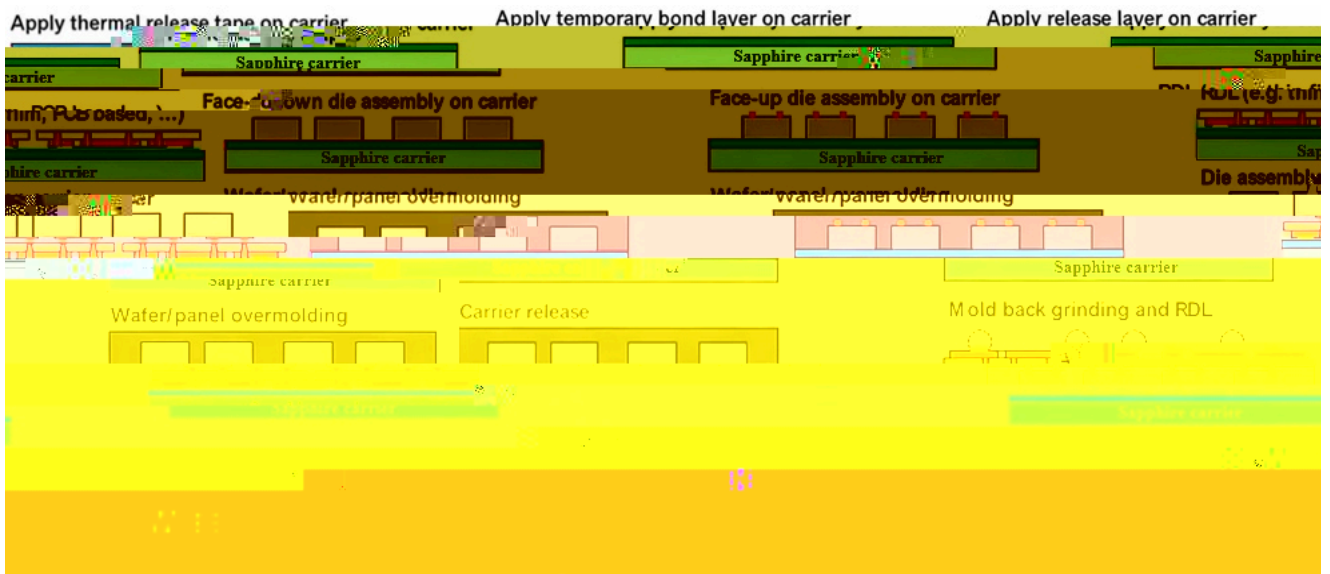
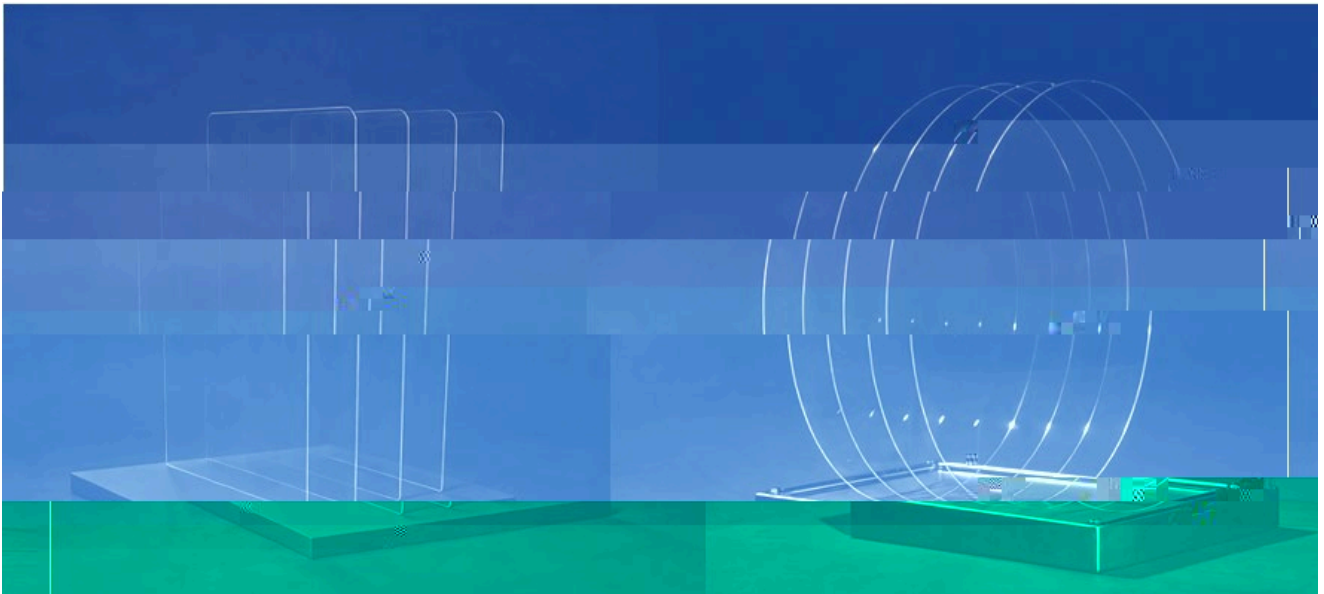


蓝宝石载盘 Sapphire Carrier

高杨氏模量 | 高机械强度 | 高透过率 | 与晶圆制程完美兼容
——适配先进封装、超薄晶圆处理场景

High Young's Modulus | High mechanical strength | High Transmittance | Perfect Compatibility with Wafer Processing
—— Suitable for advanced packaging and ultra-thin wafer processing scenarios



半导体载盘行业痛点

Pain Points in the Semiconductor Carrier Industry

当前先进封装在薄型化过程中面临的主要挑战是形变与翘曲问题。由于晶片、封装基板、底部填充胶、中介层及覆盖层等材料之间存在热膨胀系数不匹配、固化收缩以及厚度分布不对称等因素，在反复热循环过程中容易引发应力累积，进而导致结构变形。这一问题已成为封装行业在优化设计中亟需解决的关键痛点。

Current advanced packaging faces primary challenges of deformation and warpage during the thinning process. Due to factors such as mismatches in the coefficient of thermal expansion (CTE) among materials like the die, packaging substrate, underfill, interposer, and mold compound, as well as curing shrinkage and asymmetric thickness distribution, stress accumulation is prone to occur during repeated thermal cycling, which in turn leads to structural deformation. This issue has become a critical pain point that the packaging industry urgently needs to address in optimization design.

蓝宝石性能优势

Performance Advantages of Sapphire

High Young's Modulus

leM

r s o

High Young's modulus(345-420 GPa) effectively suppresses deformation and warpage

